

# **SPECIFICATION SHEET**

## Components, Inc. THICK FILM CHIP RESISTORS CASE 2012 METRIC CR05 SERIES

SPECIFICATION SHEET NO.	S0227- CR0805FB10KS01			
ORIGINAL MFG/PART NO.	Aillen Capacitors/CRO	D5FB10K		
NEXTGEN PART CODE	CR0805FB10KS01	Indicate This Code For RFQ /Order		
DATE	Feb. 27, 2025			
REVISION	A1	Updated With Most Recent Data		
DESCRIPTION AND	Thick Film Chip Resist	tors, 0805 (2012 Metric), CR05 Series,		
MAIN PARAMETRICS	Dimension L2.00*W1.25*H0.50mm, 2 Terminations, Tolerance: ±1.0%, Resistance Range 10Kohm, Dissipation Max. 1/8W @ 70°C, Temperature Coefficient Rate (TCR) Max. ±100ppm/°C Operating Temp. Range -55°C ~+155°C Package in Tape/Reel, 5,000pcs/Reel REACH/RoHS/RoHS III Compliant and HF			
CUSTOMER				
CUSTOMER PART NUMBER				
CROSS REF. PART NUMBER				
МЕМО				

### **VENDOR APPROVE**

Issued/Checked/Approved







Date: Feb. 27, 2025

CUSTOMER APPROVE	
DATE:	

2/27/2025

#### THICK FILM CHIP RESISTORS CASE 2012 METRIC CR05 SERIES

#### **DESCRIPTION**

The resistors are constructed in a high grade ceramic body (aluminum oxide).

Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to within tolerance by laser cutting of this resistive layer. The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Tin (lead free) alloy.



Image shown is a representation only. Exact specifications should be obtained from the product dimension.







#### **MAIN FEATURE**

- High Reliability And Stability
- · Reduced Size Of Final Equipment
- · Lower Assembly Costs
- · Higher Component And Equipment Reliability
- REACH/RoHS/RoHS III Compliant And Halogen Free Products

#### **APPLICATION**

- Consumer Electrical Equipment
- · EDP, Computer Application
- Telecom Application

#### **ELECTRICAL CHARBCTERISTICS**

- See Page 5 ~page 7
- All Products Parameters are Subject To NextGen Components' Final Confirmation.

#### THICK FILM CHIP RESISTORS CASE 2012 METRIC CR05 SERIES

#### **HOW TO ORDER**

• Please Follow Up Part Code Guide And Indicate Part Code <u>CR0805FB10KS01</u> For RFQ/Order.

#### **PART CODE GUIDE**



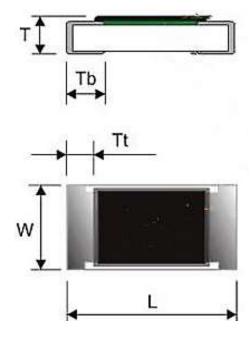
CODE	NAME	KEY SPECIFICATION OPTION
CR	Product code	Thick Film Chip Resistors
0805	Size Code	0402 (1005): L1.00*W0.50mm; 0603 (1608): L1.60*W0.80mm; 0805 (2012): L2.00*W1.25mm; 1206 (3216:) L3.20*W1.60mm;
F	Resistance Range Tolerance Code	P: Jumper; B: +/-0.1%; D: +/-0.5%; F: +/-1%; J: +/-5%
В	Package Code	A: 4Kpcs/7"Reel; B:5kpcs/7"Reel; C:10kpcs/7"Reel; M:15kpcs/7"Reel; D:10kpcs/10"Reel; E:20kpcs/10"Reel
10K	Resistance Value Code	OR: 0ohm; 1R2: 1.2ohm; 15R: 15ohm; 20R: 20ohm; 68R: 68ohm;  120R: 120ohm; 470R: 470ohm; 1K:1Kohm; 2K: 2Kohm; 5K1: 5.1Kohm;  10K: 10Kohm; 62K: 62Kohm; 100K: 100Kohm; 118K: 118Kohm;  1M: 1.0Mohm; 2M: 2Mohm
S01	Internal Control Code	Custom letter A~Z, a-z or digits (0-9)





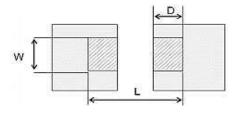
#### **DIMENSION** (Unit: mm)

Case Size:0805 (2012 metric) L2.00\*W1.25\*H0.50mm



ITEM	DIMENSION
L	2.00±0.10
W	1.25±0.10
Т	0.50±0.15
Тb	0.40±0.20
Τt	0.40±0.20

## Recommended Solder Pad



ITEM	DIMENSION
W	1.00~1.40
L	3.20~3.80
D	0.90~1.40

#### Construction For Reference



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#### **TEST CONDITIONS** - FOR JUMPER (0 ohm)

ITEM	UNIT	SYMBOL	CHARACTERISTIC	CONDITION
Power Rating	W		1/8	@ 70°C
Max. Resistance	mRΩ		50	
Rated Current	А		2.0	
Peak Current	А		3.5	

#### **GENERAL CONDITIONS - FOR DIFFERENT PART CODE**

ITEM	UNIT	SYMBOL	CHARACTERISTIC	CONDITION
Operating Temperature Range	°C		-55 ~+155	
Storage Temperature Range	°C		5~+40	

#### Note

- 1) This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"
- 2) Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by  $RCWV = \sqrt{Rated\ Power \times Resistance\ Value} \text{ or Max. RCWV listed above, whichever is lower.}$
- 3) Test condition for jumper (0  $\Omega$ )



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## **ELECTRICAL CHARACTERISTICS** - Ta = 25°C, FOR DIFFERENT PART CODE

NextGen	Original Part	Resistance	Resistance	Temp.	Max.	Max.	Max.
Part Code	Number	Tolerance	Range	Coefficient	Dissipation	Operation	Overload
				Rate	@Tamb	Voltage	Voltage
				(TRC)	70°C	(DC or RMS)	(DC or RMS)
		%	Ω	ppm/°C	W	V	V
CR0805PB0RS001	CR05PB0R	Jumper	0	-200~+400	1/8	150	300
CR0805FB12RS01	CR05FB12R	±1.0	12	±100	1/8	150	300
CR0805JB12RS01	CR05JB12R	±5.0	12	±100	1/8	150	300
CR0805JB15RS01	CR05JB15R	±5.0	15	±100	1/8	150	300
CR0805JB68RS01	CR05JB68R	±5.0	68	±100	1/8	150	300
CR0805JB100RS1	CR05JB100R	±5.0	100	±100	1/8	150	300
CR0805JB120RS1	CR05JB120R	±5.0	120	±100	1/8	150	300
CR0805JB470RS1	CR05JB470R	±5.0	470	±100	1/8	150	300
CR0805FB1KS001	CR05FB1K	±1.0	1K	±100	1/8	150	300
CR0805JB1KS001	CR05JB1K	±5.0	1K	±100	1/8	150	300
CR0805JB4K7S01	CR05JB4K7	±5.0	4.7K	±100	1/8	150	300
CR0805JB5K1S01	CR05JB5K1	±5.0	5.1K	±100	1/8	150	300
CR0805FB10KS01	CR05FB10K	±1.0	10K	±100	1/8	150	300
CR0805JB10KS01	CR05JB10K	±5.0	10K	±100	1/8	150	300
CR0805JB12KS01	CR05JB12K	±5.0	12K	±100	1/8	150	300
CR0805JB100KS1	CR05JB100K	±5.0	100K	±100	1/8	150	300
CR0805JB220KS1	CR05JB220K	±5.0	220K	±100	1/8	150	300
CR0805FB475KS1	CR05FB475K	±1.0	475K	±100	1/8	150	300
CR0805FB510KS1	CR05FB510K	±1.0	510K	±100	1/8	150	300
CR0805FB1MS001	CR05FB1M	±1.0	1M	±100	1/8	150	300



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## **ELECTRICAL CHARACTERISTICS** - Ta = 25°C, FOR DIFFERENT PART CODE

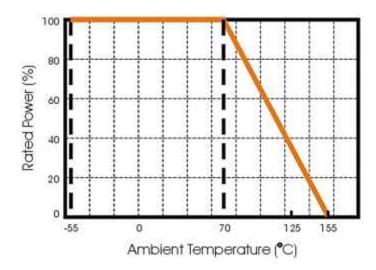
NextGen Part Code	Original Part Number	Resistance Tolerance %	Resistance Range	Temp. Coefficient Rate (TRC) ppm/°C	Max. Dissipation @Tamb 70°C	Max. Operation Voltage (DC or RMS)	Max. Overload Voltage (DC or RMS)
CR0805FB1M3S01	CR05FB1M3	±1.0	1.3M	±100	1/8	150	300
							7

#### PRODUCT CHARACTERIZATION

Standard values of nominal resistance are taken from the E24 & E96 series for resistors with a tolerance of  $\pm$ 0.1%,  $\pm$ 0.5%,  $\pm$ 1% &  $\pm$ 5%, The values of the E24/E96 series are in accordance with "IEC publication 60063"

#### **DERATING**

The power that the resistor can dissipate depends on the operating temperature; see the figure below:



Maximum dissipation in percentage of rated power as a function of the ambient temperature for CR06, CR05, CR03, CR02

#### **MOUNTING**

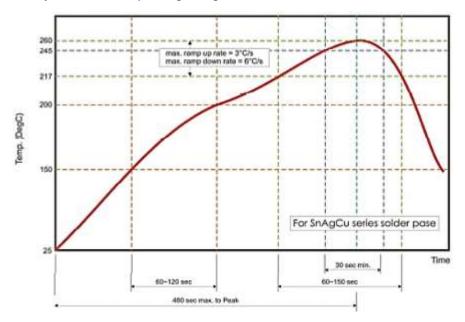
Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems. Chip placement can be on ceramic substrates and printed-circuit boards (PCBs). Electrical connection to the circuit is by individual soldering condition. The end terminations guarantee a reliable contact.

#### STORAGE AND HANDLING CONDITIONS

- 1) Products are recommended to be used up within two years since operation date as ensured shelf life. Check solderability in case shelf life extension is needed.
- 2) To store products with following condition: Temperature: 5 to 40°C Humidity: 20 to 70% relative humidity
- 3) Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering b.To store products on the shelf and avoid exposure to moisture. Don't expose products to excessive shock, vibration, direct sunlight and so on. 2/27/2025

#### REFLOW SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260 °C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs). Surface Mount Resistors are tested for solderability at 235 °C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in below.



Infrared soldering profile for Chip Resistors

#### **TEST AND REQUIREMENTS**

Essentially all tests are carried out according to the schedule of IEC publication 115-8, category LCT/UCT/56(rated temperature range: Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS. The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, subclause 5.3. Unless otherwise specified, the following value supplied

Temperature: 15 °C to 35 °C; Relative humidity: 45% to 75%.

Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar).

All soldering tests are performed with mildly activated flux



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### **TEST AND REQUIREMENT** (JIS C 5201-1 : 1998)

TEST	PROCEDURE / TEST METHOD	REQUIREMEN	NT
		Resistor	0Ω
Electrical Characteristics JISC5201-1: 1998 Clause 4.8	- DC resistance values measurement - Temperature Coefficient of Resistance (T.C.R) Natural resistance change per change in degree centigrade. $\frac{R_2-R_1}{R_1(t_2-t_1)}\times 10^6 \text{ (ppm/°C)}$ $\text{t1: } 20^\circ\text{C+5°C-1°C; t2:-55°C or +155°C}$ R1: Resistance at reference temperature $(20^\circ\text{C+5°C/- 1°C)}$ R2: Resistance at test temperature (-55°C or +155°C)	Within the specified tolerance Refer to "QUICK REFERENCE DATA"	<50mΩ
Resistance To Soldering Heat(R.S.H) JISC5201-1:1998 Clause 4.18	Un-mounted chips completely immersed for 10±1 second in a SAC solder bath at 260°C±5°C	$\pm 5\%$ : ΔR/R max. $\pm (1\% + 0.05\Omega)$ ; $\pm 1\%$ : ΔR/R max. $\pm (0.5\% + 0.05\Omega)$ no visible damage	<50mΩ
Solderability JISC5201-1: 1998 Clause 4.17	Un-mounted chips completely immersed for 2±0.5 second in a SAC solder bath at 235°C±5°C	95% coverage min., g	
Temperature cycling JISC5201-1: 1998 Clause 4.19	30 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 30 minutes at +125°C±3°C, 2~3 minutes at 20°C+5°C1°C, total 5 continuous cycles	$\pm 5\%$ : ΔR/R max. $\pm (1\% + 0.05\Omega)$ ; $\pm 1\%$ : ΔR/R max. $\pm (0.5\% + 0.05\Omega)$ no visible damage	<50mΩ
High Temperature Exposure MIL-STD-202 method 108	1000+48/-0 hours; without load in a temperature chamber controlled 155 3 C	$\pm 5\%$ : $\Delta R/R$ max. $\pm (2\%+0.1\Omega)$ ; $\pm 1\%$ : $\Delta R/R$ max. $\pm (1\%+0.1\Omega)$ no visible damage	<50mΩ

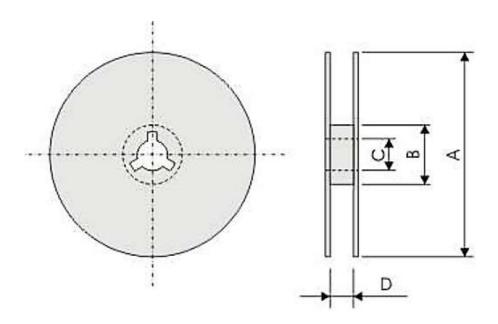


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### **TEST AND REQUIREMENT** (JIS C 5201-1 : 1998)

TEST	PROCEDURE / TEST METHOD	REQUIREMENT		
		Resistor	0Ω	
Bending strength JISC5201-1: 1998 Clause 4.33	Resistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec, 5mm for CR02	$\pm 5\%$ : $\Delta R/R$ max. $\pm (1\%+0.05\Omega)$ ; $\pm 1\%$ : $\Delta R/R$ max. $\pm (1\%+0.05\Omega)$ no visible damage	<50mΩ	
Adhesion JISC5201-1: 1998 Clause 4.32	Pressurizing force: 5N, Test time: 10±1sec	No remarkable dama removal of the termi		
Short Time Overload (STOL) JISC5201-1: 1998 Clause 4.13	2.5 times RCWV or max. overload voltage, for 5seconds	$\pm$ 5%: ΔR/R max. $\pm$ (2%+0.05Ω); $\pm$ 1%: ΔR/R max. $\pm$ (1%+0.05Ω) no visible damage	<50mΩ	
Load life in Humidity JISC5201-1: 1998 Clause 4.24	1000 +48/-0 hours, loaded with RCWV or Vmax in humidity chamber controller at 40 C 2 C and 90~95% relative humidity, 1.5hours on and 0.5 hours off	$\pm 5\%$ : $\Delta R/R$ max. $\pm (2\%+0.1\Omega)$ ; $\pm 1\%$ : $\Delta R/R$ max. $\pm (1\%+0.1\Omega)$ no visible damage	<50mΩ	
Load life (endurance) JISC5201-1: 1998 Clause 4.25	1000 +48/-0 hours, loaded with RCWV or Vmax in chamber controller 70±2°C, 1.5 hours on and 0.5 Hours off	$\pm 5\%$ : $\Delta R/R$ max. $\pm (3\%+0.1\Omega)$ ; $\pm 1\%$ : $\Delta R/R$ max. $\pm (1\%+0.1\Omega)$ no visible damage	<50mΩ	
Insulation Resistance JISC5201-1: 1998 Clause 4.6	Apply the maximum overload voltage (DC) for 1minute	R ≥ 10GΩ		
Dielectric Withstand Voltage JISC5201-1: 1998 Clause 4.7	Apply the maximum overload voltage (AC) for 1 minute	No breakdown or fla	shover	

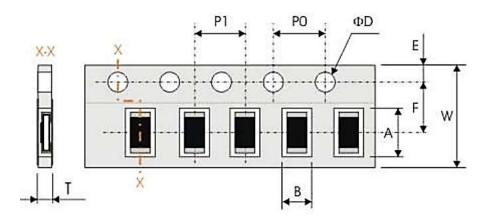
### REEL DIMENSION (Unit: mm)



CODE	DIMENSION 7" Reel	DIMENSION 10" Reel	DIMENSION 13" Reel
А	Ø178.0±2.0	Ø254.0±2.0	Ø330.0±2.0
В	Ø60.0 ±1.0	Ø100 ±1.0	Ø100±1.0
С	13.0±0.20	13.0±0.20	13.0±0.20
D	9.0±0.50	9.0±0.50	9.0±0.50



## TAPE DIMENSION (Unit: mm)



CODE	DIMENSION
А	2.40±0.20
В	1.65±0.20
W	8.00±0.30
F	3.50±0.20
E	1.75±0.10
P 1	4.00±0.10
PO	4.00±0.10
ФД	1.50+0.10/-0.0
Т	1.0 Max.

#### **TAPING QUANTITY**

TAPE	PAPER TAPE					EMBOSSED TAPE	BULK CASSETTE	
	4 mm Pitch 2 mm Pitch					4 mm Pitch		
Reel Size	7"	10"	13"	7"	10"	13"	7"	
CR05	5000	10000	20000				-	10000
0/07/0005								13

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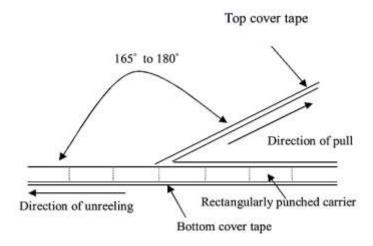
#### PERFORMANCE OF TAPING

Strength of Carrier Tape and Top Cover Tape

Carrier Tape: When a tensile force 1.02kgf is applied in the direction of unreeling the tape, the tape shall withstand this force. Top cover Tape: When a tensile force 1.02kgf is applied to the tape, the tape shall withstand this force.

Peel Force of Top Cover Tape

Unless otherwise specified, the peel force of top cover tape shall be 10.2 to 71.4 g f when the top cover tape is pulled at a speed of 300mm/min with the angle between the taped during peel and the direction of unreeling maintained at 165 to 180° as illustrated in Fig.



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#### **CAUTION**

- Don't apply excess mechanical stress to the component and terminals at soldering. Do not use this product with bend.
- Do not clean or wash the component for it is not hermetically sealed.
- Do not use strong acidity flux, more than 0.2wt% chlorine content, in flow soldering.
- Don't be close to fire.
- This specification mentions the quality of the component as a single unit. Please insure the component is thoroughly evaluated in your application circuit
- Expire date (Shelf life) of the products is 12 months after delivery under the conditions of a sealed and an
  unopened package. Please use the products within 12 months after delivery. If you store the products for a
  long time (more than 12 months), use carefully because the products may be degraded in the solder-ability or
  rusty. Please confirm solder-ability and characteristics for the products regularly.
- Exposure components under soldering condition that is exceeding our recommendation will increase the failure dangerous.
- Please contact us before using the product as automobile electronic component.
- Please return one of these specifications after your signature of acceptance.
- When something gets doubtful with this specifications, we shall jointly work to get an agreement.
- For questions on technology, prices and delivery, please contact our sales offices or e-mail: sales@NextGenComponent.com

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#### **IMPORTANT NOTES AND DISCLAIMER**

- ROHS COMPLIANCE: The levels of RoHS restricted materials in this product are below the maximum
  concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an
  exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for
  this product can be obtained can be obtained at Download Center.
- REACH COMPLIANCE: REACH substances of high concern (SVHCs) information is available for this product.
   Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained at Download Center.
- All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test
  conditions, unless otherwise noted. Product performance may not be indicated by the Electrical
  Characteristics if operated under different conditions.
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